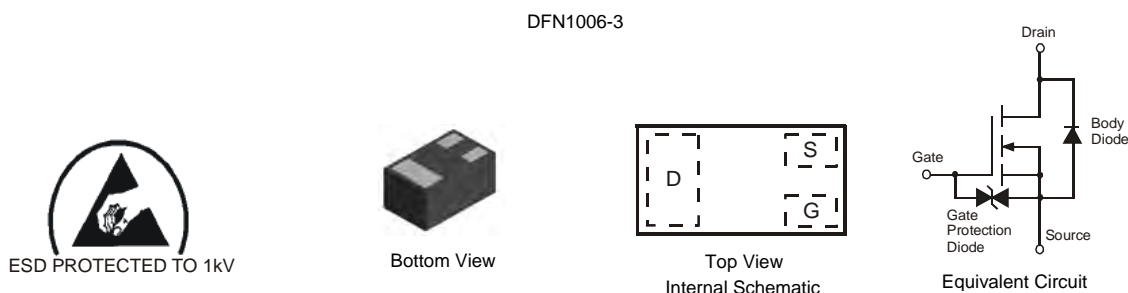


Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **ESD Protected Gate 1kV**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)

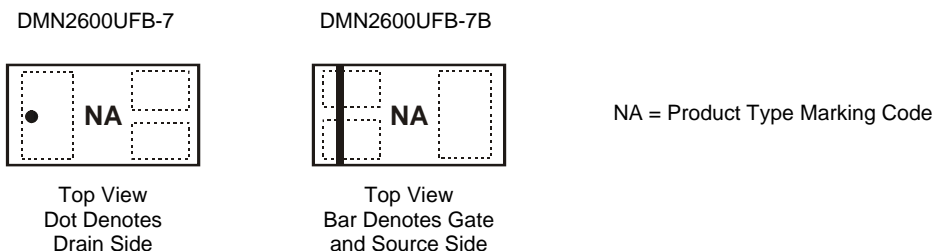


Ordering Information (Note 3)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN2600UFB-7	NA	7	8	3000
DMN2600UFB-7B	NA	7	8	10,000

- Notes:
1. No purposefully added lead
 2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	25	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 4)	Steady State	T _A = 25°C	I _D	1.3	A
		T _A = 85°C		0.9	
Pulsed Drain Current			I _{DM}	3.0	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	0.54	W
Thermal Resistance, Junction to Ambient @T _A = 25°C	R _{θJA}	234	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	25	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1	μA	V _{DS} = 25V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	10	μA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.45	-	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	-	350	mΩ	V _{GS} = 4.5V, I _D = 200mA
				450		V _{GS} = 2.5V, I _D = 100mA
				600		V _{GS} = 1.8V, I _D = 75mA
Forward Transfer Admittance	Y _{fs}	40	-	-	mS	V _{DS} = 3V, I _D = 200mA
Diode Forward Voltage	V _{SD}	-	-	1.2	V	V _{GS} = 0V, I _S = 300mA
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}	-	70.13	-	pF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	7.56	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	5.59	-	pF	
Gate Resistance	R _g	-	72.3	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	-	0.85	-	nC	V _{GS} = 4.5V, V _{DS} = 15V, I _D = 1A
Gate-Source Charge	Q _{gs}	-	0.16	-	nC	
Gate-Drain Charge	Q _{gd}	-	0.11	-	nC	
Turn-On Delay Time	t _{D(on)}	-	4.1	-	ns	V _{DS} = 15V, R _L = 15Ω V _{GS} = 10V, R _G = 6Ω
Turn-On Rise Time	t _r	-	11.5	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	34.8	-	ns	
Turn-Off Fall Time	t _f	-	20.9	-	ns	

- Notes:
- Device mounted on FR-4 substrate PCB board, with minimum recommended pad layout.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

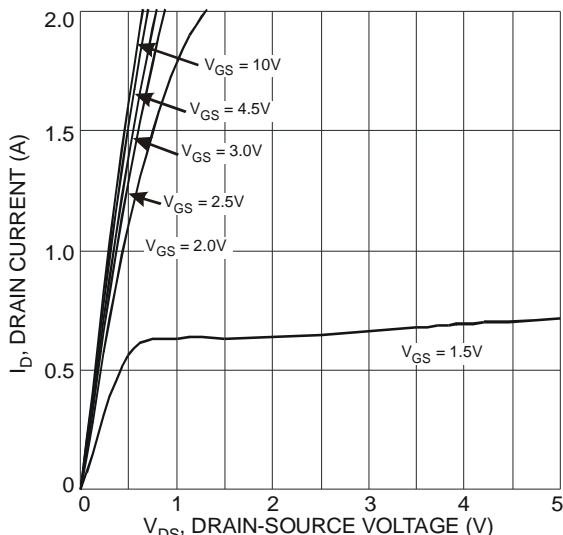


Fig. 1 Typical Output Characteristic

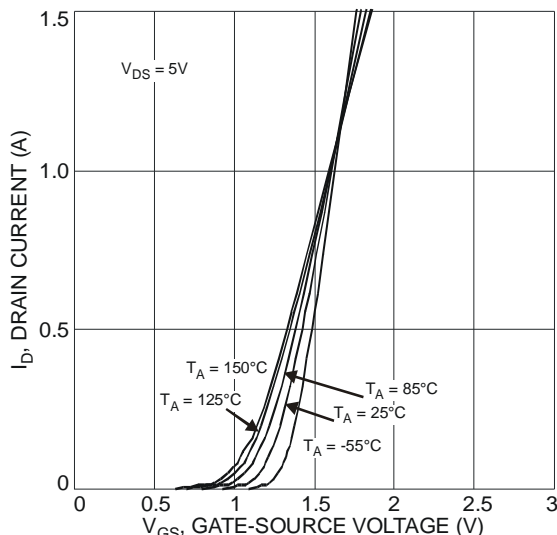


Fig. 2 Typical Transfer Characteristic

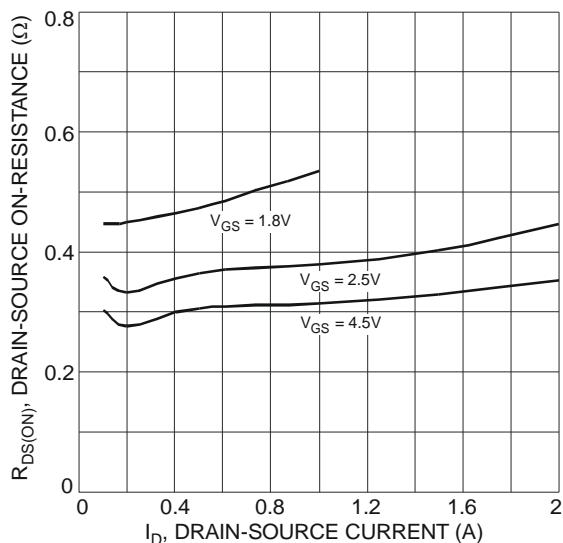


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

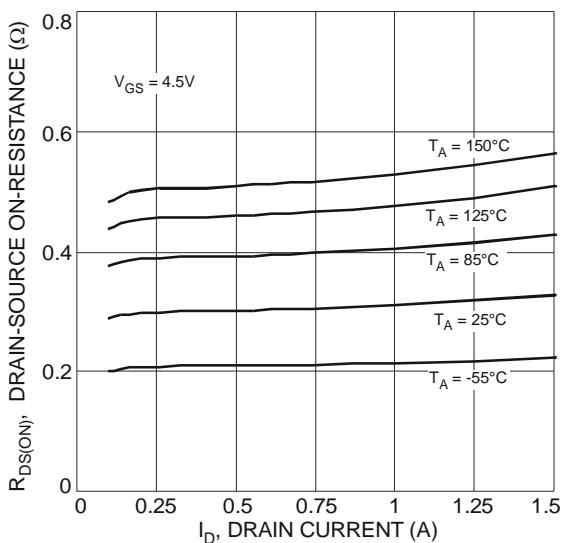


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

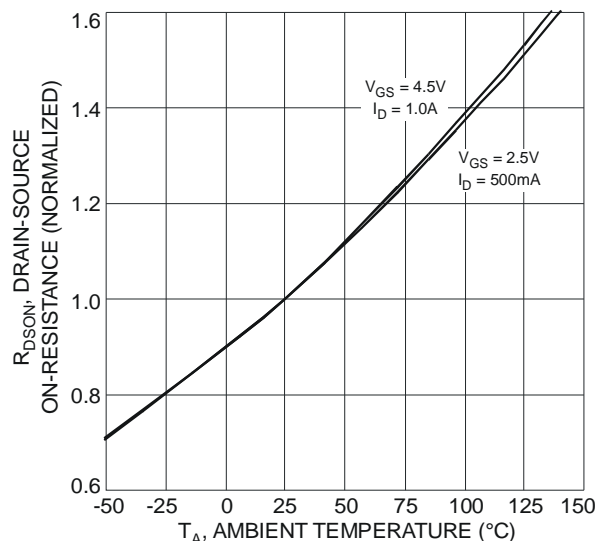


Fig. 5 On-Resistance Variation with Temperature

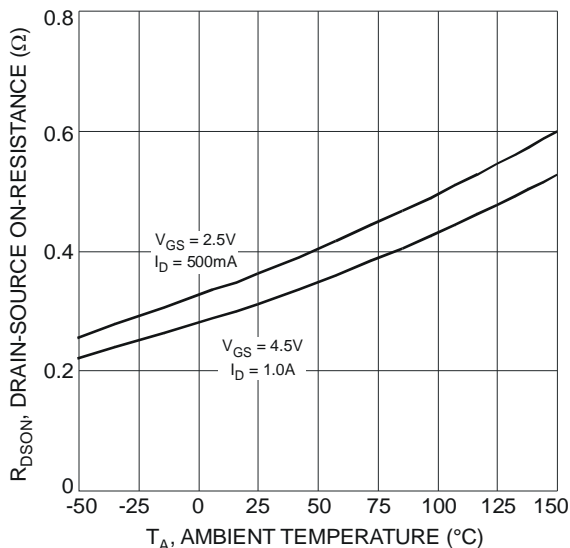


Fig. 6 On-Resistance Variation with Temperature

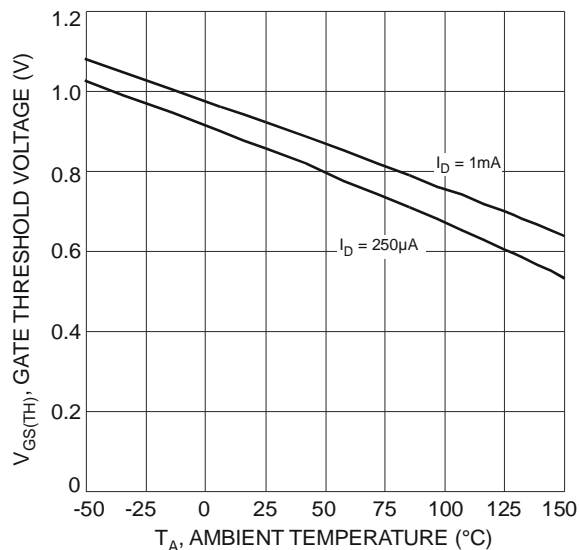


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

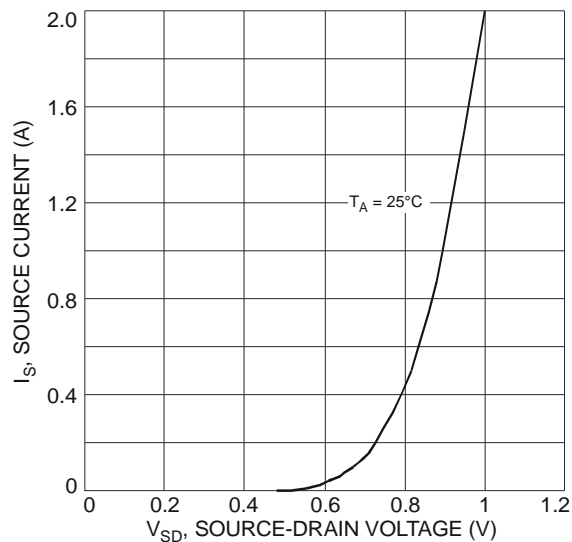


Fig. 8 Diode Forward Voltage vs. Current

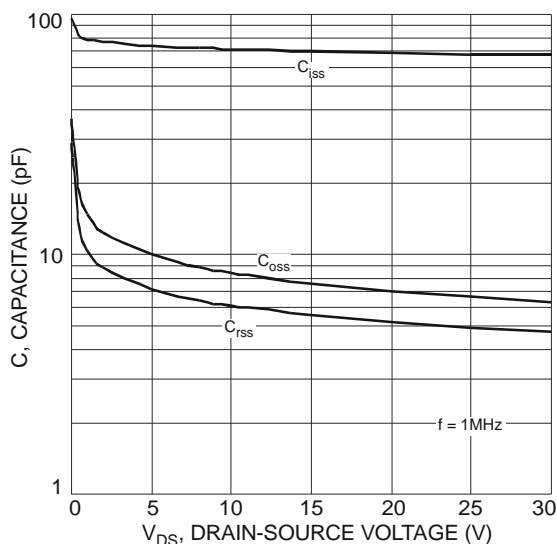


Fig. 9 Typical Total Capacitance

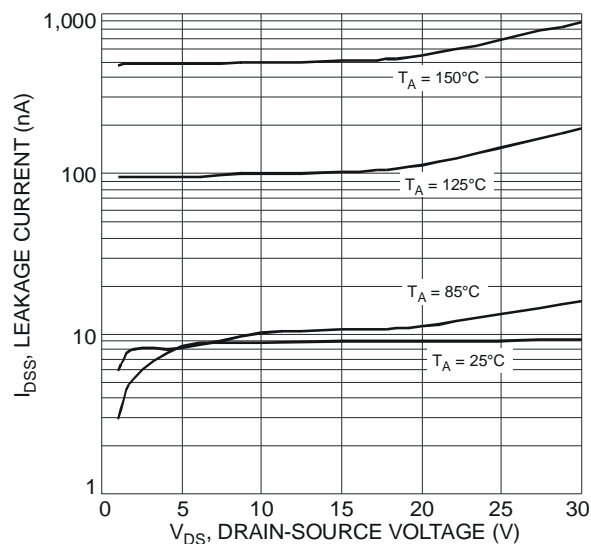


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

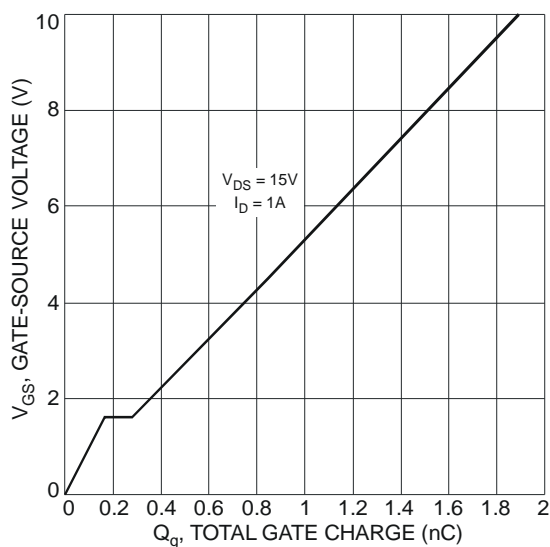


Fig. 11 Gate-Charge Characteristics

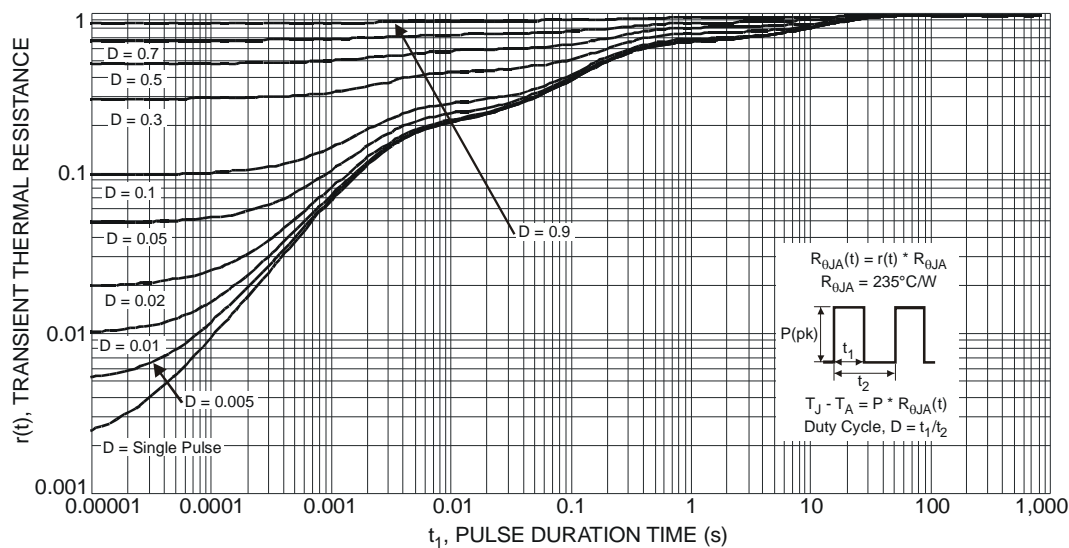
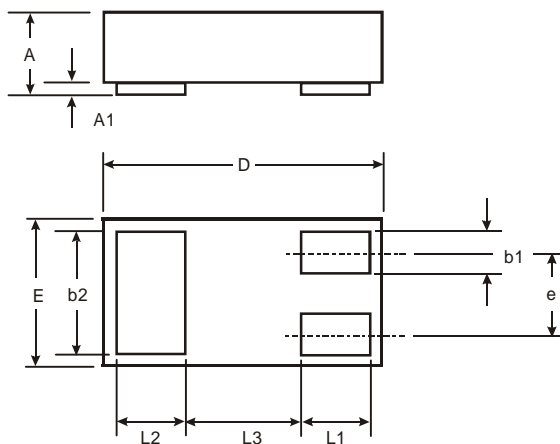


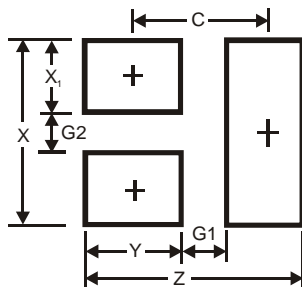
Fig. 12 Transient Thermal Response

Package Outline Dimensions



DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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